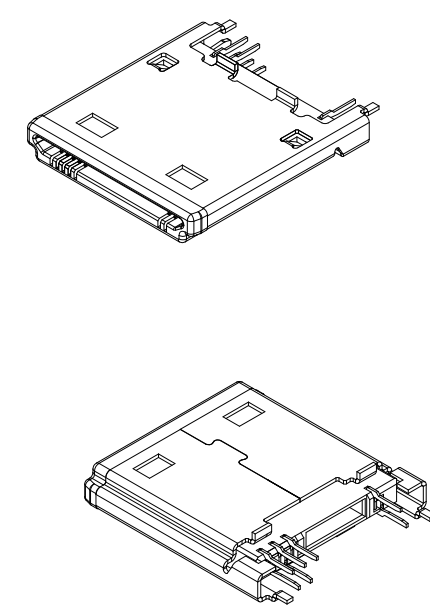
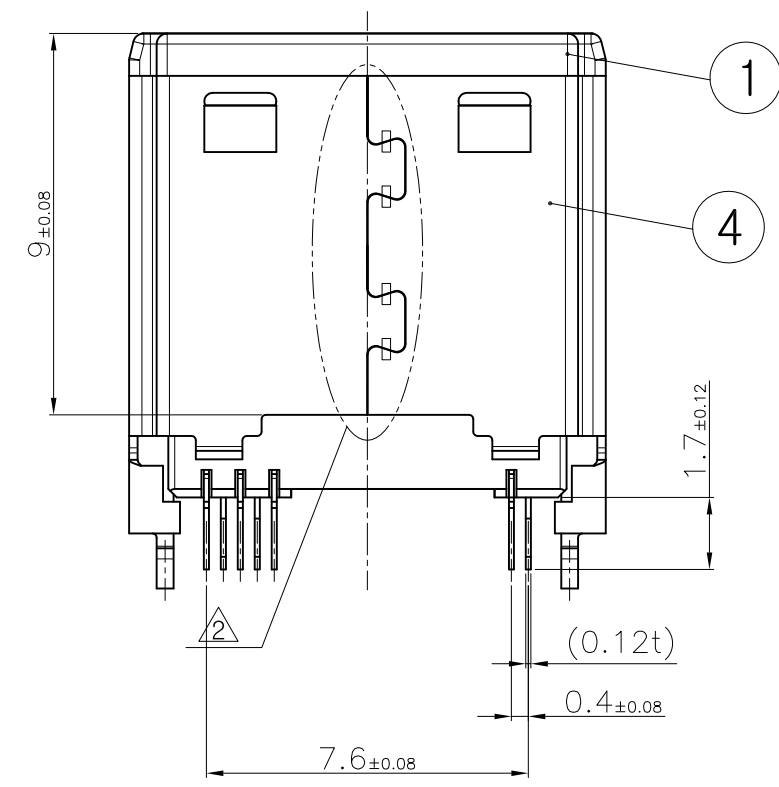
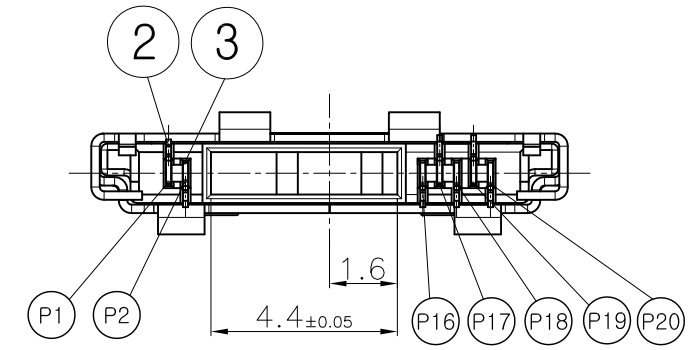
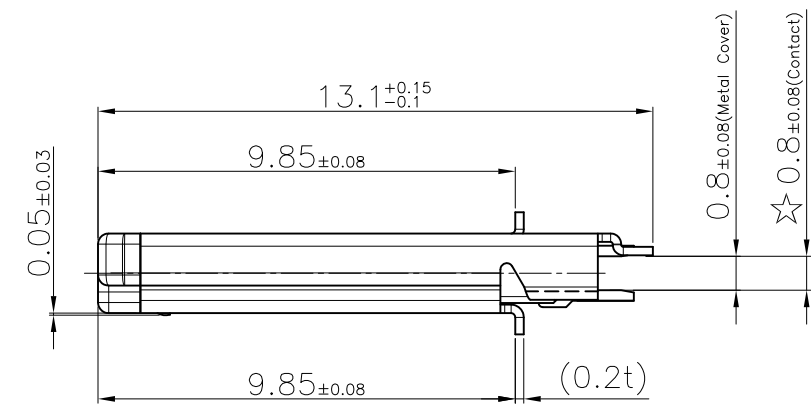
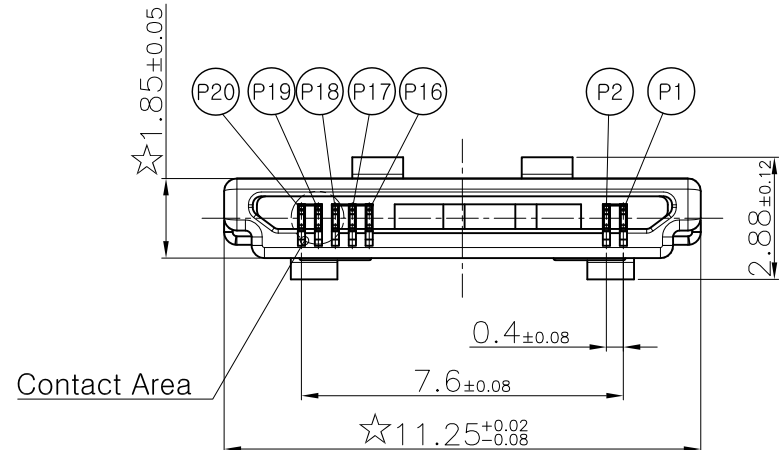
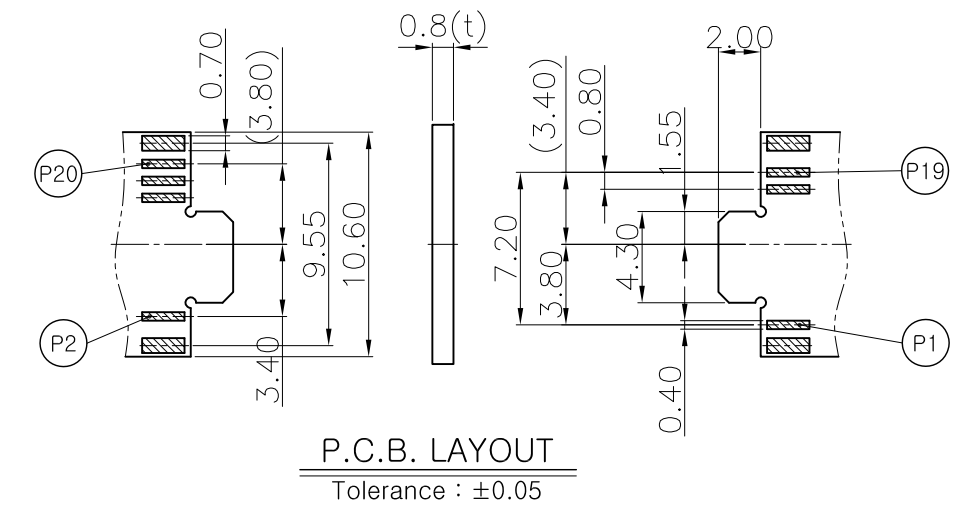
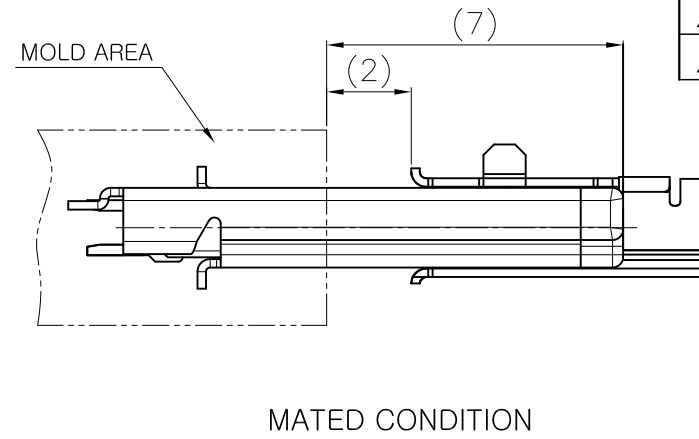
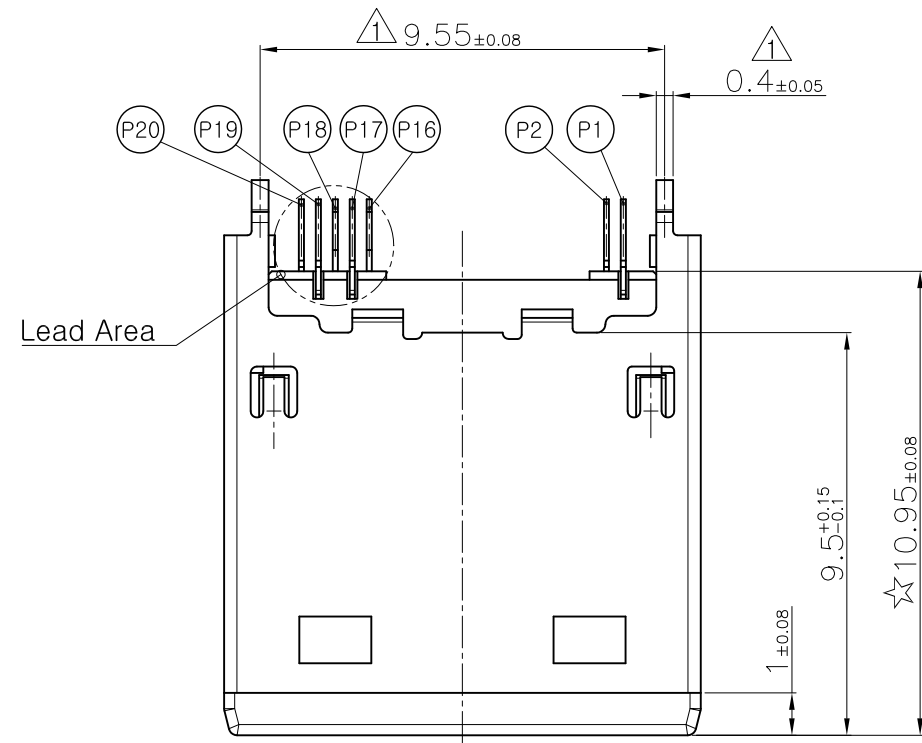


변경번호	변경 사항	변경일	작성	승인	시방변경 No.
△1 X 2	고객요청에 의한 M/C 형상변경	07/09/27	BS PARK		070927-01
△2 X 2	접합부 1개소 --> 2개소 변경/ 원재료변경	08/05/13	JKPARK	KY CHOI	080513-01
△3 X 2	CONTACT 원재료 변경	08/07/22	JKPARK	KY CHOI	090206-02
△4 X 2	M/C 및 CONTACT 도금 변경	09/03/13	GW KIM	SC LEE	090507-02



-Note -

- Plating
 - CONTACT TER'
 - Contact Area : Au 0.3μm over Ni 1.0~5.0μm
 - Lead Area : Au 0.03μm over Ni 1.0~3.0μm
 - METAL COVER : Ni 1.0~5.0μm (부분 도금)
 - Lead부 Ni 1.0~5.0μm (부분 도금)
- ☆ = C.T.Q

No	Descriptions	Material	Finish	Remarks
4	Metal Cover	△3 STS304 3/4H	Note.	t0.2
3	CONTACT "B"	△3 C5210 COPPER ALLOY(M702S)	Note.	t0.12
2	CONTACT "A"	△3 C5210 COPPER ALLOY(M702S)	Note.	t0.12
1	HOUSING	△2 PA46(EN568)	Black color	UL94V-2

지시하지 않은 일반공차		척도	N/S	단위	mm	매수	1 of 1		품명	S20 PLUG	
치수	mm (°)	날짜	2007. 06. 25							HY20-AC0350(7P)	
X	± 0.2	제도	설계	검도	심사	승인			CUSTOMER DRAWING		
X.X	± 0.1	BS PARK						SW No.	HY20-AC0350-A1.DWG	Rev.	
X.XX	± 0.05							DWG No.	HY20-AC0350-A1	4	
X.XXX	± 0.01										
ANGLE	± 1°										

HJ&C HYUP JIN I&C CO., LTD.